- **State-of-the-Art *EPIC*-II*B*™ BiCMOS Design Significantly Reduces Power Dissipation**

- **Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17**

- **Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C**

- **High-Drive Outputs (–32-mA I_{OH}, 64-mA I_{OL})**

- **ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)**

- **Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK), Plastic (N) and Ceramic (J) DIPs, and Ceramic Flat (W) Package**

SN54ABT377 . . . J OR W PACKAGE
SN74ABT377A . . . DB, DW, N, OR PW PACKAGE
(TOP VIEW)

$\overline{\text{CLKEN}}$	1	20	V_{CC}
1Q	2	19	8Q
1D	3	18	8D
2D	4	17	7D
2Q	5	16	7Q
3Q	6	15	6Q
3D	7	14	6D
4D	8	13	5D
4Q	9	12	5Q
GND	10	11	CLK
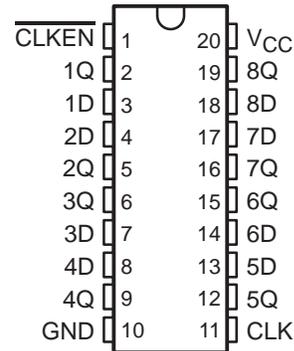
SN54ABT377 . . . FK PACKAGE
(TOP VIEW)

Top pins: 1D (3), 1Q (2), $\overline{\text{CLKEN}}$ (1), V_{CC} (20), 8Q (19)

2D	4	18	8D
2Q	5	17	7D
3Q	6	16	7Q
3D	7	15	6Q
4D	8	14	6D

Bottom pins: 4Q (9), GND (10), CLK (11), 5Q (12), 5D (13)

description

These 8-bit positive-edge-triggered D-type flip-flops with a clock (CLK) input are particularly suitable for implementing buffer and storage registers, shift registers, and pattern generators.

Data (D) input information that meets the setup time requirements is transferred to the Q outputs on the positive-going edge of the clock pulse if the common clock-enable ($\overline{\text{CLKEN}}$) input is low. Clock triggering occurs at a particular voltage level and is not directly related to the transition time of the positive-going pulse. When the buffered clock (CLK) input is at either the high or low level, the D-input signal has no effect at the output. The circuits are designed to prevent false clocking by transitions at $\overline{\text{CLKEN}}$.

The SN54ABT377 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT377A is characterized for operation from –40°C to 85°C.

FUNCTION TABLE
(each flip-flop)

INPUTS			OUTPUT
$\overline{\text{CLKEN}}$	CLK	D	Q
H	X	X	Q_0
L	↑	H	H
L	↑	L	L
X	H or L	X	Q_0

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

EPIC-IIB is a trademark of Texas Instruments Incorporated.

TEXAS INSTRUMENTS

logic symbol†

† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)

To Seven Other Channels

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} .... −0.5 V to 7 V
Input voltage range, V_I (see Note 1) .... −0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O .... −0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABT377 .... 96 mA
  SN74ABT377A .... 128 mA
Input clamp current, I_{IK} ($V_I < 0$) .... −18 mA
Output clamp current, I_{OK} ($V_O < 0$) .... −50 mA
Package thermal impedance, θ_{JA} (see Note 2): DB package .... 115°C/W
  DW package .... 97°C/W
  N package .... 67°C/W
  PW package .... 128°C/W
Storage temperature range, T_{stg} .... −65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
  2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except for through-hole packages, which use a trace length of zero.

recommended operating conditions (see Note 3)

			SN54ABT377		SN74ABT377A		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current			−24		−32	mA
I_{OL}	Low-level output current			48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		5		5	ns/V
T_A	Operating free-air temperature		−55	125	−40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		$T_A = 25°C$			SN54ABT377		SN74ABT377A		UNIT
			MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}	$V_{CC} = 4.5$ V,	$I_I = -18$ mA			−1.2		−1.2		−1.2	V
V_{OH}	$V_{CC} = 4.5$ V,	$I_{OH} = -3$ mA	2.5			2.5		2.5		V
	$V_{CC} = 5$ V,	$I_{OH} = -3$ mA	3			3		3		
	$V_{CC} = 4.5$ V	$I_{OH} = -24$ mA	2			2				
		$I_{OH} = -32$ mA	2*					2		
V_{OL}	$V_{CC} = 4.5$ V	$I_{OL} = 48$ mA			0.55		0.55			V
		$I_{OL} = 64$ mA			0.55*				0.55	
V_{hys}				100						mV
I_I	$V_{CC} = 5.5$ V,	$V_I = V_{CC}$ or GND			±1		±1		±1	µA
I_{off}	$V_{CC} = 0$,	V_I or $V_O ≤ 4.5$ V			±100				±100	µA
I_{CEX}	$V_{CC} = 5.5$ V,	$V_O = 5.5$ V	Outputs high			50		50		50	µA
I_O‡	$V_{CC} = 5.5$ V,	$V_O = 2.5$ V	−50	−100	−180	−50	−180	−50	−180	mA
I_{CC}	$V_{CC} = 5.5$ V, $I_O = 0$, $V_I = V_{CC}$ or GND	Outputs high		1	250		250		250	µA
		Outputs low		24	30		30		30	mA
ΔI_{CC}§	$V_{CC} = 5.5$ V, One input at 3.4 V, Other inputs at V_{CC} or GND				1.5		1.5		1.5	mA
C_i	$V_I = 2.5$ V or 0.5 V			3.5						pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.
† All typical values are at $V_{CC} = 5$ V.
‡ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
§ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

			SN54ABT377				UNIT
			$V_{CC} = 5$ V, $T_A = 25°C$		MIN	MAX	
			MIN	MAX			
f_{clock}	Clock frequency		0	150	0	150	MHz
t_w	Pulse duration	CLK high or low	3.3		3.3		ns
t_{su}	Setup time before CLK↑	Data high or low	2		2.5		ns
		CLKEN high or low	3		3		
t_h	Hold time after CLK↑	Data high or low	1.8¶		1.8¶		ns
		CLKEN high or low	1.8¶		1.8¶		

¶ This data sheet limit may vary among suppliers.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

			SN74ABT377A				UNIT
			V_{CC} = 5 V, T_A = 25°C		MIN	MAX	
			MIN	MAX			
f_{clock}	Clock frequency		0	150	0	150	MHz
t_w	Pulse duration	CLK high or low	3.3		3.3		ns
t_{su}	Setup time before CLK↑	Data high or low	2		2.5		ns
		$\overline{\text{CLKEN}}$ high or low	3		3		
t_h	Hold time after CLK↑	Data high or low	1.8[†]		1.8[†]		ns
		$\overline{\text{CLKEN}}$ high or low	1.2[†]		1.2[†]		

[†] This data sheet limit may vary among suppliers.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54ABT377					UNIT
			V_{CC} = 5 V, T_A = 25°C			MIN	MAX	
			MIN	TYP	MAX			
f_{max}			150			150		MHz
t_{PLH}	CLK	Q	2.2	4.5	6	2.2	7	ns
t_{PHL}			3.1	5.3	6.8	2	7.6	

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN74ABT377A					UNIT
			V_{CC} = 5 V, T_A = 25°C			MIN	MAX	
			MIN	TYP	MAX			
f_{max}			150			150		MHz
t_{PLH}	CLK	Q	2.2	4.5	6	2.2	6.5	ns
t_{PHL}			2.6[†]	5.3	6.8	2.6[†]	7.3	

[†] This data sheet limit may vary among suppliers.

TEXAS
INSTRUMENTS
POST OFFICE BOX 655303 ● DALLAS, TEXAS 75265

PARAMETER MEASUREMENT INFORMATION
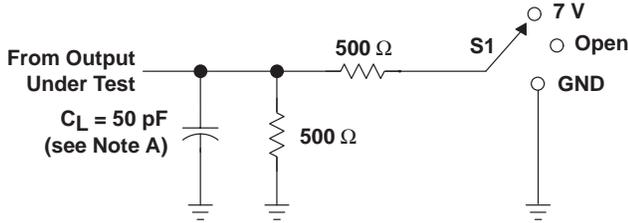
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open

**LOAD CIRCUIT**
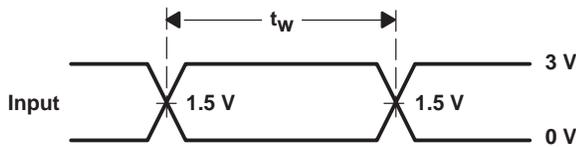
VOLTAGE WAVEFORMS
PULSE DURATION
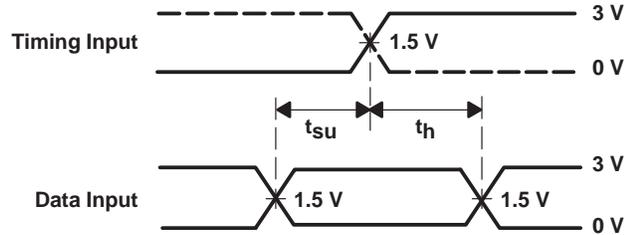
VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES
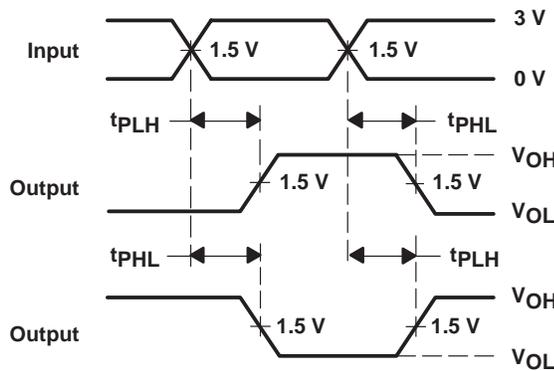
VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS
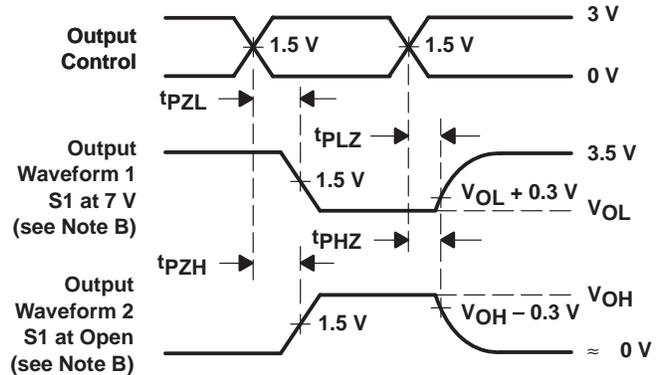
VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
   B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control.
       Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
   C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
   D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status [1]	Package Type	Package Drawing	Pins	Package Qty	Eco Plan [2]	Lead/ Ball Finish	MSL Peak Temp [3]	Samples (Requires Login)
5962-9314801Q2A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Call TI	
5962-9314801QRA	ACTIVE	CDIP	J	20	1	TBD	Call TI	Call TI	
5962-9314801QSA	ACTIVE	CFP	W	20	1	TBD	Call TI	Call TI	
SN74ABT377ADBLE	OBSOLETE	SSOP	DB	20		TBD	Call TI	Call TI	
SN74ABT377ADBR	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ABT377ADBRE4	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ABT377ADBRG4	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ABT377ADW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ABT377ADWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ABT377ADWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ABT377ADWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ABT377ADWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ABT377AN	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74ABT377ANE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74ABT377ANSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ABT377ANSRE4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ABT377ANSRG4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ABT377APW	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ABT377APWE4	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	

Orderable Device	Status [1]	Package Type	Package Drawing	Pins	Package Qty	Eco Plan [2]	Lead/ Ball Finish	MSL Peak Temp [3]	Samples (Requires Login)
SN74ABT377APWG4	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ABT377APWLE	OBSOLETE	TSSOP	PW	20		TBD	Call TI	Call TI	
SN74ABT377APWR	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ABT377APWRE4	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ABT377APWRG4	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SNJ54ABT377FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
SNJ54ABT377J	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	
SNJ54ABT377W	ACTIVE	CFP	W	20	1	TBD	Call TI	N / A for Pkg Type	

[1] The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

[2] Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

[3] MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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OTHER QUALIFIED VERSIONS OF SN54ABT377 :

● Catalog: SN74ABT377

NOTE: Qualified Version Definitions:

     ● Catalog - TI's standard catalog product

TAPE AND REEL INFORMATION

REEL DIMENSIONS
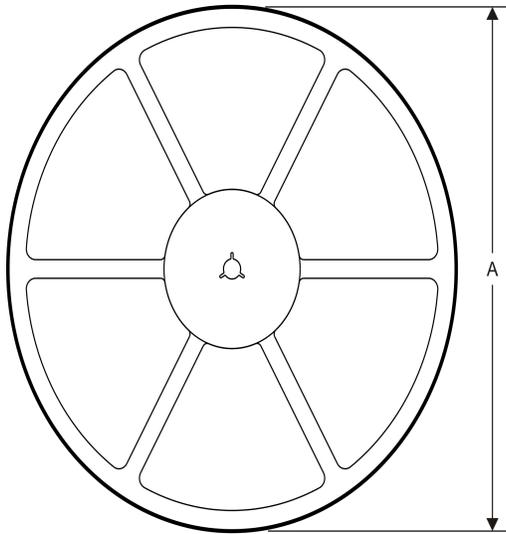
TAPE DIMENSIONS

A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ABT377ADBR	SSOP	DB	20	2000	330.0	16.4	8.2	7.5	2.5	12.0	16.0	Q1
SN74ABT377ADWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1
SN74ABT377ANSR	SO	NS	20	2000	330.0	24.4	8.2	13.0	2.5	12.0	24.0	Q1
SN74ABT377APWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ABT377ADBR	SSOP	DB	20	2000	367.0	367.0	38.0
SN74ABT377ADWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN74ABT377ANSR	SO	NS	20	2000	367.0	367.0	45.0
SN74ABT377APWR	TSSOP	PW	20	2000	367.0	367.0	38.0

J (R—GDIP—T**)   CERAMIC DUAL IN—LINE PACKAGE
14 LEADS SHOWN

DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	——	——	——	——
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)

B

14   8

1   7

0.065 (1,65)
0.045 (1,14)

C

0.005 (0,13) MIN

0.060 (1,52)
0.015 (0,38)

0.200 (5,08) MAX

Seating Plane

0.130 (3,30) MIN

0.026 (0,66)
0.014 (0,36)

0.100 (2,54)

A

0°—15°

0.014 (0,36)
0.008 (0,20)

4040083/F 03/03

NOTES: A. All linear dimensions are in inches (millimeters).
        B. This drawing is subject to change without notice.
        C. This package is hermetically sealed with a ceramic lid using glass frit.
        D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
        E. Falls within MIL STD 1835 GDIP1—T14, GDIP1—T16, GDIP1—T18 and GDIP1—T20.

W (R–GDFP–F20)   CERAMIC DUAL FLATPACK
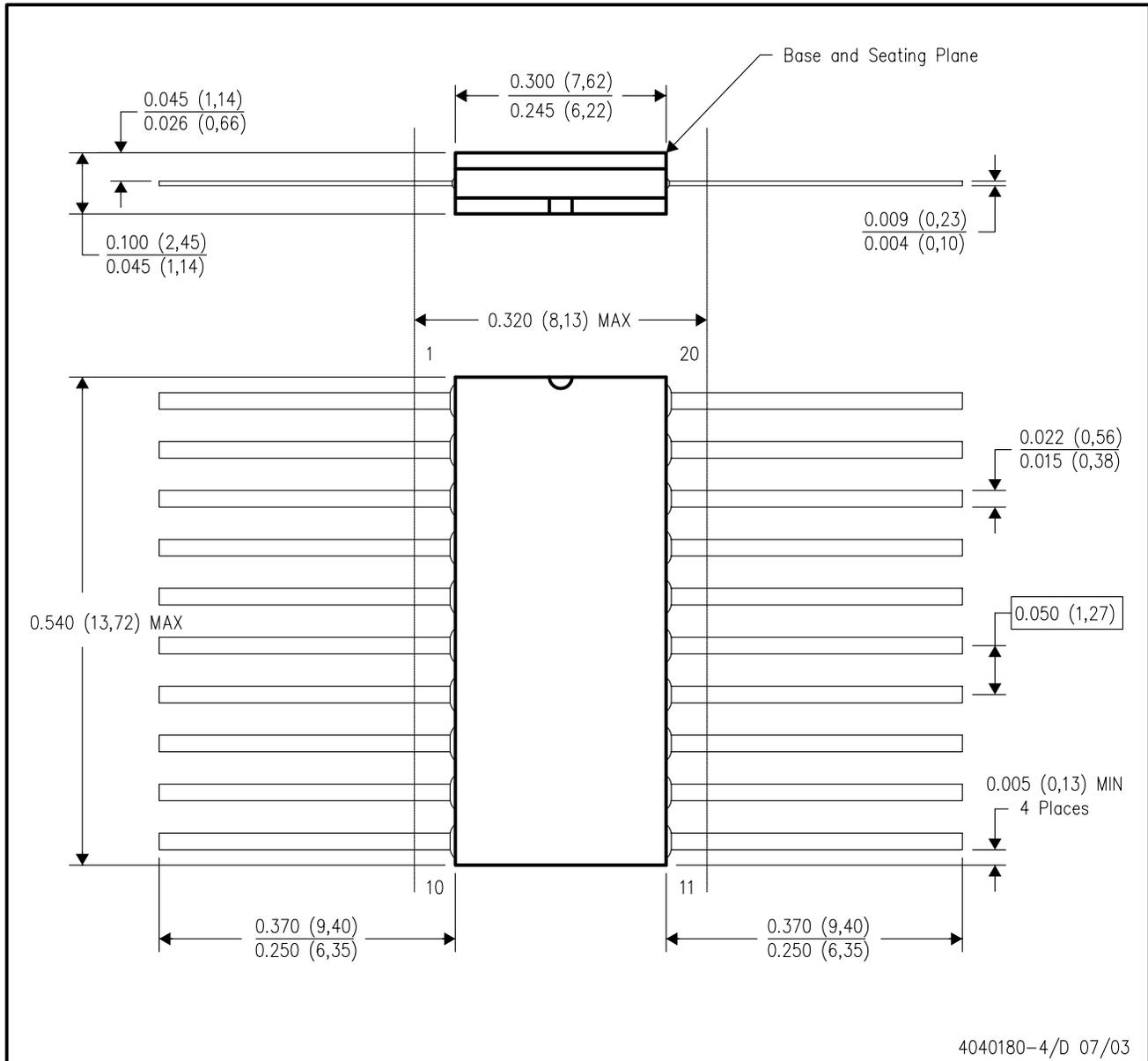
Base and Seating Plane

0.300 (7,62) / 0.245 (6,22)

0.045 (1,14) / 0.026 (0,66)

0.009 (0,23) / 0.004 (0,10)

0.100 (2,45) / 0.045 (1,14)

0.320 (8,13) MAX

1   20

0.022 (0,56) / 0.015 (0,38)

0.540 (13,72) MAX

0.050 (1,27)

0.005 (0,13) MIN
4 Places

10   11

0.370 (9,40) / 0.250 (6,35)

0.370 (9,40) / 0.250 (6,35)

4040180–4/D 07/03

NOTES: A.   All linear dimensions are in inches (millimeters).
         B.   This drawing is subject to change without notice.
         C.   This package can be hermetically sealed with a ceramic lid using glass frit.
         D.   Index point is provided on cap for terminal identification only.
         E.   Falls within Mil–Std 1835 GDFP2–F20

FK (S−CQCC−N**)   LEADLESS CERAMIC CHIP CARRIER
28 TERMINAL SHOWN
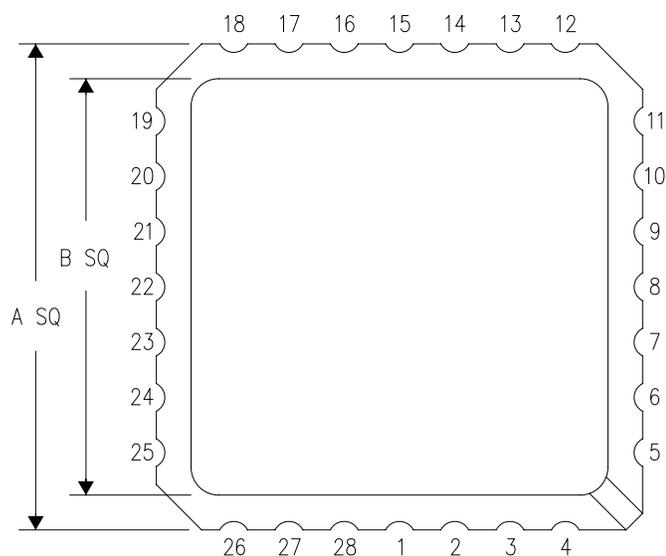
NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.740 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)

B SQ
A SQ

$\dfrac{0.020\ (0,51)}{0.010\ (0,25)}$

$\dfrac{0.020\ (0,51)}{0.010\ (0,25)}$

$\dfrac{0.080\ (2,03)}{0.064\ (1,63)}$

$\dfrac{0.055\ (1,40)}{0.045\ (1,14)}$

$\dfrac{0.045\ (1,14)}{0.035\ (0,89)}$

$\dfrac{0.028\ (0,71)}{0.022\ (0,54)}$

0.050 (1,27)

$\dfrac{0.045\ (1,14)}{0.035\ (0,89)}$
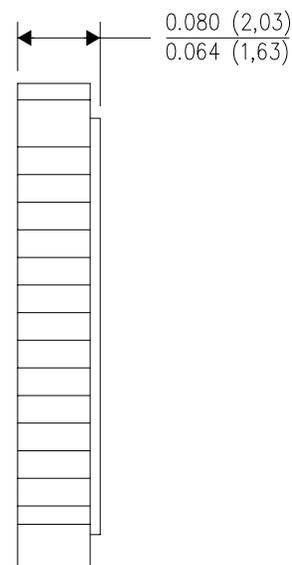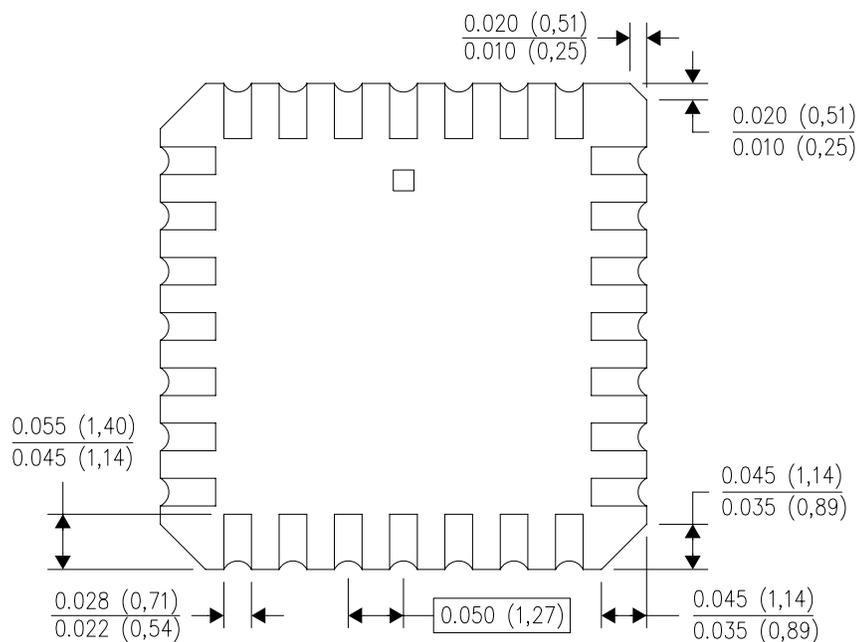
4040140/D 01/11

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a metal lid.
D. Falls within JEDEC MS−004

TEXAS
INSTRUMENTS
www.ti.com

N (R−PDIP−T**)   **PLASTIC DUAL−IN−LINE PACKAGE**

16 PINS SHOWN

DIM ＼ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
⚠C MS−001 VARIATION	AA	BB	AC	AD

A

16   9

$\dfrac{0.260 \ (6,60)}{0.240 \ (6,10)}$

1   8

$\dfrac{0.070 \ (1,78)}{0.045 \ (1,14)}$ ⚠D

$\dfrac{0.045 \ (1,14)}{0.030 \ (0,76)}$ ⚠D

0.020 (0,51) MIN

0.200 (5,08) MAX

Seating Plane

0.125 (3,18) MIN

0.100 (2,54)

$\dfrac{0.021 \ (0,53)}{0.015 \ (0,38)}$

⊕ 0.010 (0,25) Ⓜ

$\dfrac{0.325 \ (8,26)}{0.300 \ (7,62)}$

0.015 (0,38)

Gauge Plane

0.010 (0,25) NOM

0.430 (10,92) MAX

14/18 Pin Only
20 Pin vendor option ⚠D

4040049/E   12/2002

NOTES: A. All linear dimensions are in inches (millimeters).
            B. This drawing is subject to change without notice.
       ⚠C Falls within JEDEC MS−001, except 18 and 20 pin minimum body length (Dim A).
       ⚠D The 20 pin end lead shoulder width is a vendor option, either half or full width.

TEXAS INSTRUMENTS
www.ti.com

DW (R−PDSO−G20)   PLASTIC SMALL OUTLINE

0.512 (13,00)
0.496 (12,60)

20   11

0.419 (10,63)
0.393 (9,97)

0.299 (7,60)
0.291 (7,40)

1   10

Pin 1
Index Area

0.050 (1,27)

0.020 (0,51)
0.012 (0,31)

⊕ 0.010 (0,25) Ⓜ

0.104 (2,65) Max

0.012 (0,30)
0.004 (0,10)

0.013 (0,33)
0.008 (0,20)

0.004 (0,10)

Gauge Plane

Seating Plane

0.010 (0,25)

0°−8°

0.050 (1,27)
0.016 (0,40)

4040000−4/G 01/11
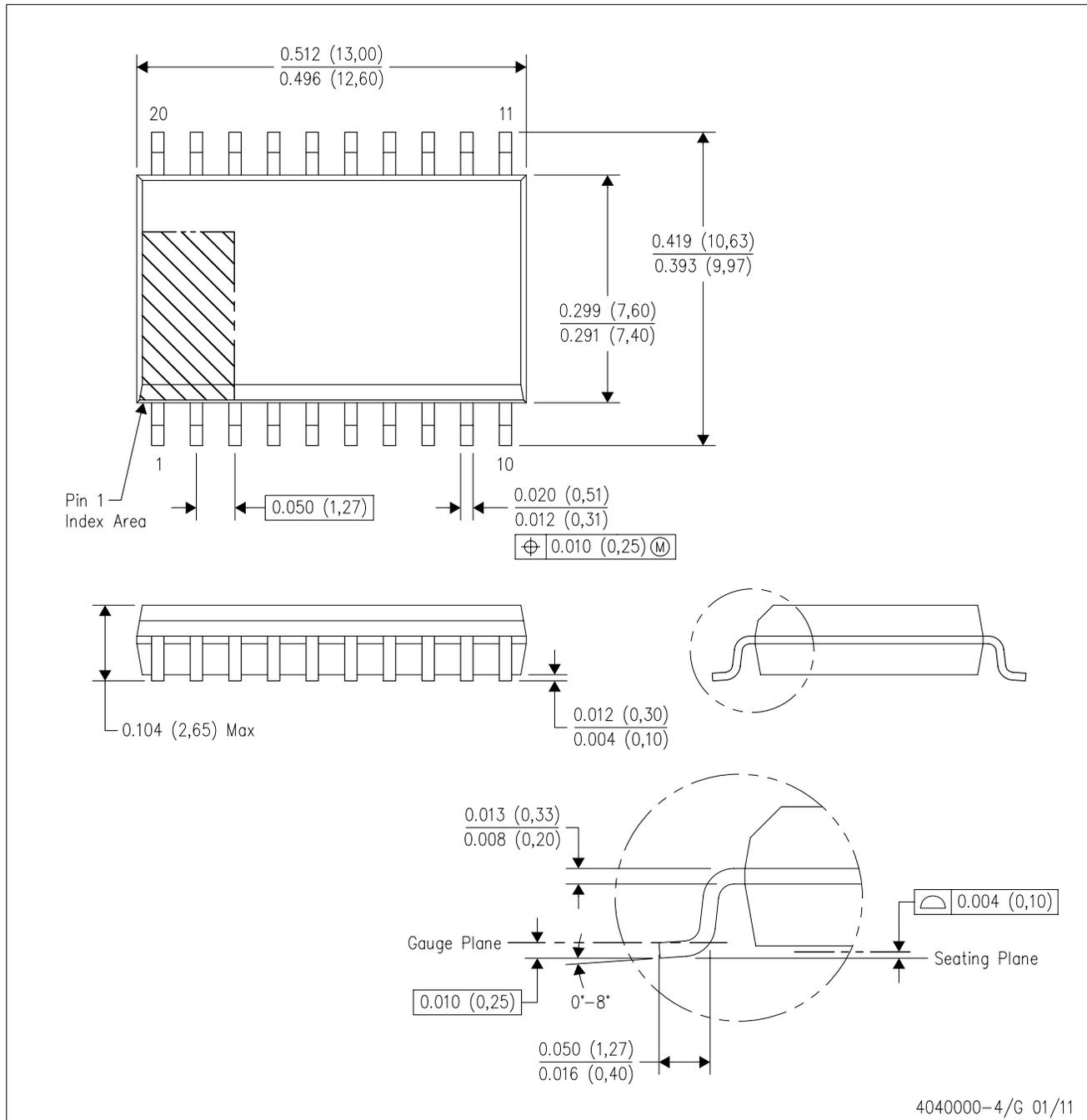
NOTES: A.   All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M−1994.
         B.   This drawing is subject to change without notice.
         C.   Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
         D.   Falls within JEDEC MS−013 variation AC.

PW (R−PDSO−G20)   PLASTIC SMALL OUTLINE

0,65

0,30
0,19

⊕ | 0,10 Ⓜ

20   11

Ⓓ   4,50
     4,30

6,60
6,20

1   10

6,60
6,40

Ⓒ

0,15 NOM

Gage Plane

0°−8°

0,25

0,75
0,50

1,20 MAX

0,15
0,05

Seating Plane

△ | 0,10

4040064−5/G 02/11

NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M−1994.
         B. This drawing is subject to change without notice.
         Ⓒ Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall
             not exceed 0,15 each side.
         Ⓓ Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
         E. Falls within JEDEC MO−153

TEXAS INSTRUMENTS
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PW (R–PDSO–G20)   PLASTIC SMALL OUTLINE

Example Board Layout

Based on a stencil thickness
of .127mm (.005inch).

18x0,65

20x0,25

1,55

5,6

5,6

18x0,65

Example
Non Soldermask Defined Pad

Example
Solder Mask Opening
(See Note F)

0,3

1,6

Pad Geometry

0,07
All Around

4211284–5/E 07/12

NOTES: A. All linear dimensions are in millimeters.
         B. This drawing is subject to change without notice.
         C. Publication IPC–7351 is recommended for alternate design.
         D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should
             contact their board assembly site for stencil design recommendations. Refer to IPC–7525 for other stencil recommendations.
         E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

MECHANICAL DATA

NS (R-PDSO-G)**   PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN
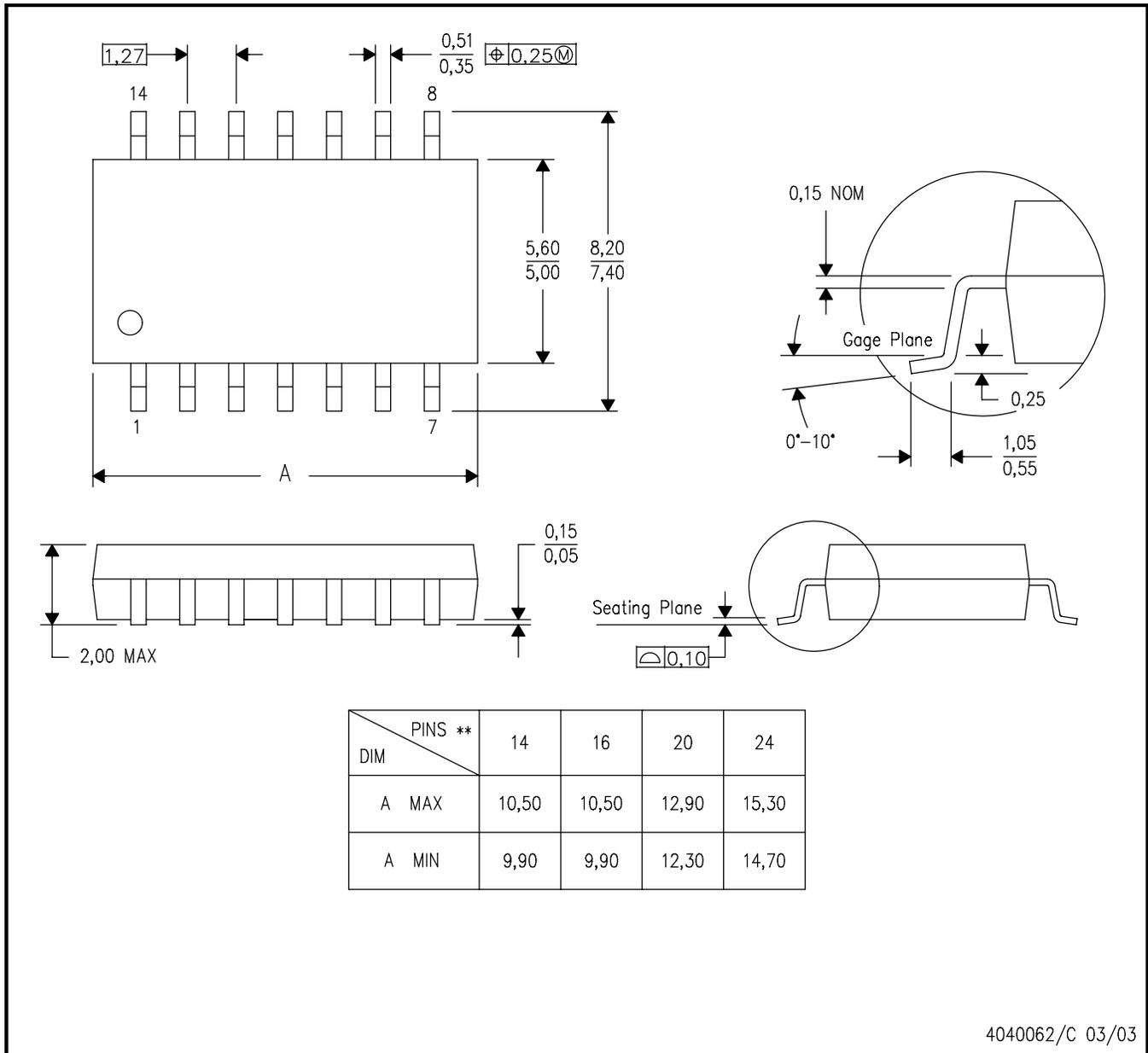
DIM	PINS **	14	16	20	24
A MAX		10,50	10,50	12,90	15,30
A MIN		9,90	9,90	12,30	14,70

4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.
        B. This drawing is subject to change without notice.
        C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

DB (R-PDSO-G**)   **PLASTIC SMALL-OUTLINE**

28 PINS SHOWN
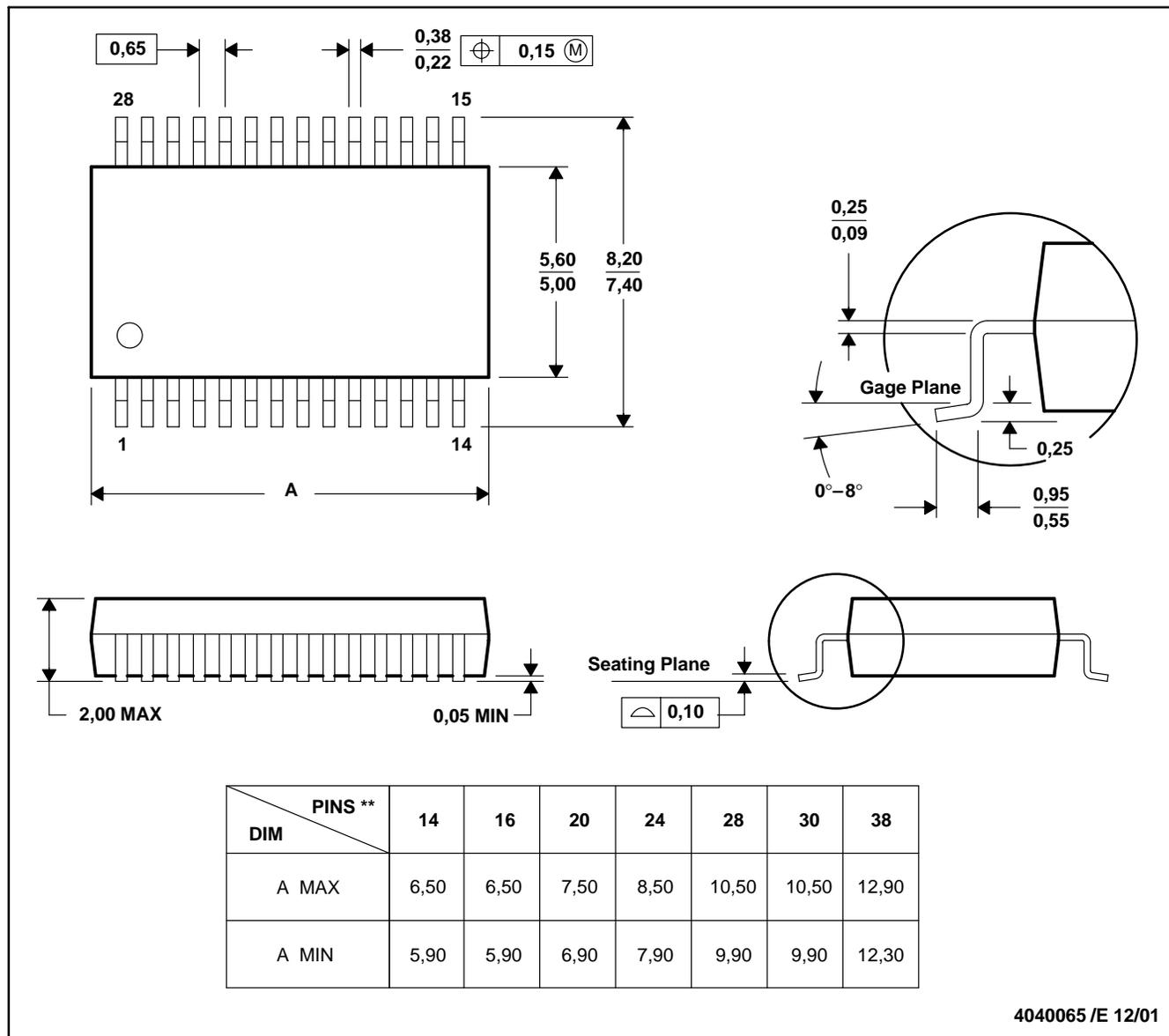
PINS ** DIM	14	16	20	24	28	30	38
A MAX	6,50	6,50	7,50	8,50	10,50	10,50	12,90
A MIN	5,90	5,90	6,90	7,90	9,90	9,90	12,30

4040065 /E 12/01

NOTES: A. All linear dimensions are in millimeters.
           B. This drawing is subject to change without notice.
           C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
           D. Falls within JEDEC MO-150

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